

L Number	Hits	Search Text	DB	Time stamp
1	181	(planariz\$3 near layer) same (etch\$3 near stop)	USPAT; US-PGPUB	2002/09/18 15:14
2	45	((planariz\$3 near layer) same (etch\$3 near stop)) and @pd<19960920	USPAT; US-PGPUB	2002/09/18 15:16
3	45	((planariz\$3 near layer) same (etch\$3 near stop)) and @pd<19960920 and (polish\$3 or planariz\$3)	USPAT; US-PGPUB	2002/09/18 15:17
4	0	((planariz\$3 near layer) same (etch\$3 near stop)) and @pd<19960920 and (polish\$3 or planariz\$3)) and ((etch\$3 near stop) near (tungsten or "w"))	USPAT; US-PGPUB	2002/09/18 15:18
5	30	((planariz\$3 near layer) same (etch\$3 near stop)) and @pd<19960920 and (polish\$3 or planariz\$3)) and (tungsten or "w")	USPAT; US-PGPUB	2002/09/18 15:29
6	6	((planariz\$3 near layer) same (etch\$3 near stop)) and @pd<19960920 and (polish\$3 or planariz\$3)) and (tungsten or "w")) and (copper or "Cu")	USPAT; US-PGPUB	2002/09/18 15:50
7	7377	(polish\$3 or planariz\$3) same (copper or "Cu")	USPAT; US-PGPUB	2002/09/18 15:53
8	1	((polish\$3 or planariz\$3) same (copper or "Cu")) and (((planariz\$3 near layer) same (etch\$3 near stop)) and @pd<19960920 and (polish\$3 or planariz\$3)) and (tungsten or "w"))	USPAT; US-PGPUB	2002/09/18 15:52
9	1340	((polish\$3 or planariz\$3) same (copper or "Cu")) and (phosphoric acid and abrasive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/18 16:13
10	118	((polish\$3 or planariz\$3) same (copper or "Cu")) and (phosphoric acid and abrasive)) and ((etch\$3 stop) near5 (tungsten or "w"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/18 16:01
11	18	((polish\$3 or planariz\$3) same (copper or "Cu")) and (phosphoric acid and abrasive)) and ((etch\$3 stop) near5 (tungsten or "w"))) and @pd<19960920	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/18 16:01
12	475	((polish\$3 or planariz\$3) same (copper or "Cu")) and ((phosphoric acid or "H.sub.3 PO.sub.4") same slurry)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/18 16:20
15	77	((polish\$3 or planariz\$3) same (copper or "Cu")) and ((phosphoric acid or "H.sub.3 PO.sub.4") same slurry)) and @pd<19960920	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/18 17:19
16	24	((polish\$3 or planariz\$3) same (copper or "Cu")) and ((phosphoric acid or "H.sub.3 PO.sub.4") same slurry)) and @pd<19960920 and ("pH" same (phosphoric acid or "H.sub.3 PO.sub.4"))	USPAT; US-PGPUB	2002/09/18 17:21
17	5	((polish\$3 or planariz\$3) same (copper or "Cu")) and ((phosphoric acid or "H.sub.3 PO.sub.4") same slurry)) and @pd<19960920 and ("pH" same (phosphoric adj acid or "H.sub.3 PO.sub.4"))	USPAT; US-PGPUB	2002/09/18 17:22
18	5	((polish\$3 or planariz\$3) same (copper or "Cu")) and ((phosphoric acid or "H.sub.3 PO.sub.4") same slurry)) and @pd<19960920 and ("pH" same (phosphoric adj acid or "H.sub.3 PO.sub.4"))) and (weight near percent or "%")	USPAT; US-PGPUB	2002/09/18 17:22